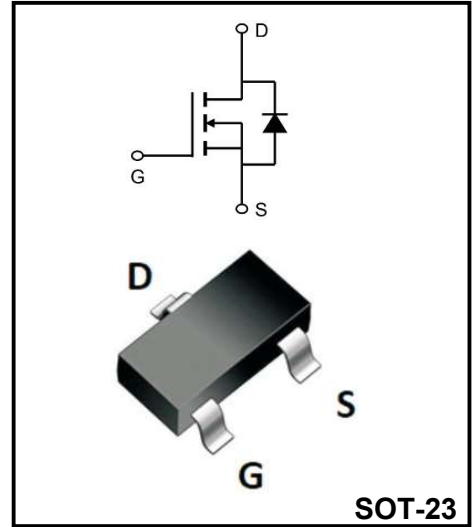


**40V N-CHANNEL ENHANCEMENT MODE MOSFET**

**MAIN CHARACTERISTICS**

<b>I<sub>D</sub></b>	3A
<b>V<sub>DSS</sub></b>	40V
<b>R<sub>DS(on)-typ</sub>(@V<sub>GS</sub>=10V)</b>	<40mΩ ( <b>Type:28 mΩ</b> )



**Description**

The YFW3N04A uses advanced trench technology to provide excellent R<sub>DS(ON)</sub>, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

**Application**

- ◆Wireless charging
- ◆Boost driver
- ◆LED

**Product Specification Classification**

Part Number	Package	Marking	Pack
YFW3N04A	SOT-23	3N04A AP	3000PCS/Tape

**Absolute Maximum Ratings (TC=25°C unless otherwise noted)**

Parameter	Symbol	Rating	Units
Drain-Source Voltage	V <sub>DS</sub>	40	V
Gate-Source Voltage	V <sub>GS</sub>	±20	V
Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	I <sub>D@TA=25°C</sub>	3	A
Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	I <sub>D@TA=70°C</sub>	2.9	A
Pulsed Drain Current <sup>2</sup>	I <sub>DM</sub>	15	A
Single Pulse Avalanche Energy <sup>3</sup>	EAS	16.2	mJ
Total Power Dissipation <sup>4</sup>	P <sub>D@TA=25°C</sub>	1.67	W
Storage Temperature Range	T <sub>STG</sub>	-55 to 150	°C
Operating Junction Temperature Range	T <sub>J</sub>	-55 to 150	°C
Thermal Resistance Junction-Ambient <sup>1</sup>	R <sub>θJA</sub>	125	°C/W
Thermal Resistance Junction-Case <sup>1</sup>	R <sub>θJC</sub>	30	°C/W

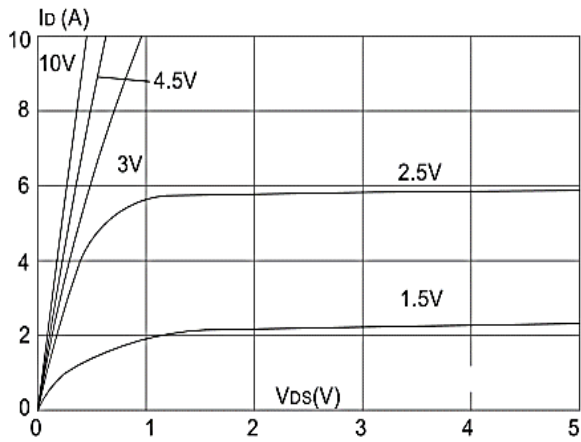
**Maximum Ratings at Tc=25°C unless otherwise specified**

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	<b>BVDSS</b>	$V_{GS}=0V, I_D=250\mu A$	40	44	---	<b>V</b>
BVDSS Temperature Coefficient	$\Delta BVDSS/\Delta T_J$	Reference to 25°C, $I_D=1mA$	---	0.032	---	<b>V/°C</b>
Static Drain-Source On-Resistance <sup>2</sup>	<b>R<sub>DS(on)</sub></b>	$V_{GS}=10V, I_D=4A$	---	28	40	<b>mΩ</b>
		$V_{GS}=4.5V, I_D=3A$	---	35	50	
Gate Threshold Voltage	<b>V<sub>GS(th)</sub></b>	$V_{GS}=V_{DS}, I_D=250\mu A$	1.0	1.5	2.5	<b>V</b>
V <sub>GS(th)</sub> Temperature Coefficient	$\Delta V_{GS(th)}$		---	-4.5	---	<b>mV/°C</b>
Drain-Source Leakage Current	<b>I<sub>DSS</sub></b>	$V_{DS}=32V, V_{GS}=0V, T_J=25°C$	---	---	1	<b>μA</b>
		$V_{DS}=32V, V_{GS}=0V, T_J=55°C$	---	---	5	
Gate-Source Leakage Current	<b>I<sub>GSS</sub></b>	$V_{GS}=\pm 20V, V_{DS}=0V$	---	---	±100	<b>nA</b>
Forward Transconductance	<b>g<sub>fs</sub></b>	$V_{DS}=5V, I_D=4A$	---	8	---	<b>S</b>
Gate Resistance	<b>R<sub>g</sub></b>	$V_{DS}=0V, V_{GS}=0V, f=1MHz$	---	2.4	4.8	<b>Ω</b>
Total Gate Charge (4.5V)	<b>Q<sub>g</sub></b>	$V_{DS}=15V, V_{GS}=4.5V, I_D=3A$	---	5	---	<b>nC</b>
Gate-Source Charge	<b>Q<sub>gs</sub></b>		---	1.54	---	
Gate-Drain Charge	<b>Q<sub>gd</sub></b>		---	1.84	---	
Turn-On Delay Time	<b>T<sub>d(on)</sub></b>	$V_{DD}=15V, V_{GS}=10V, R_G=3.3\Omega, I_D=1A$	---	7.8	---	<b>ns</b>
Rise Time	<b>T<sub>r</sub></b>		---	2.1	---	
Turn-Off Delay Time	<b>T<sub>d(off)</sub></b>		---	29	---	
Fall Time	<b>T<sub>f</sub></b>		---	2.1	---	
Input Capacitance	<b>C<sub>iss</sub></b>	$V_{DS}=15V, V_{GS}=0V, f=1MHz$	---	452	---	<b>pF</b>
Output Capacitance	<b>C<sub>oss</sub></b>		---	51	---	
Reverse Transfer Capacitance	<b>C<sub>rss</sub></b>		---	38	---	
Continuous Source Current <sup>1,4</sup>	<b>I<sub>S</sub></b>	$V_G=V_D=0V, \text{Force Current}$	---	---	4.5	<b>A</b>
Pulsed Source Current <sup>2,4</sup>	<b>I<sub>SM</sub></b>		---	---	14	<b>A</b>
Diode Forward Voltage <sup>2</sup>	<b>V<sub>SD</sub></b>	$V_{GS}=0V, I_S=1A, T_J=25°C$	---	---	1.2	<b>V</b>

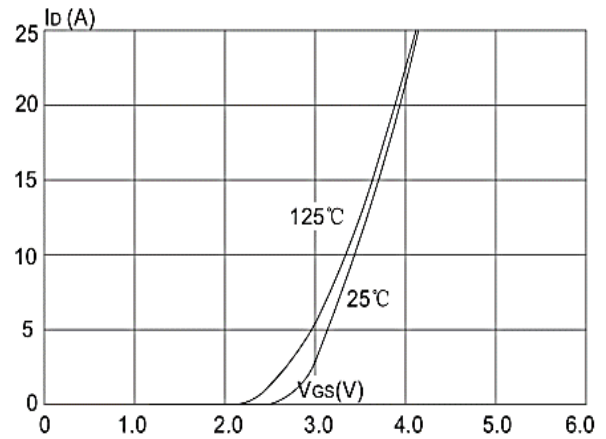
**Note :**

- 1、 The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2、 The data tested by pulsed , pulse width  $\leq 300\mu s$  , duty cycle  $\leq 2\%$
- 3、 The power dissipation is limited by 150°C junction temperature
- 4、 The data is theoretically the same as  $I_D$  and  $I_{DM}$  , in real applications , should be limited by total power dissipation.

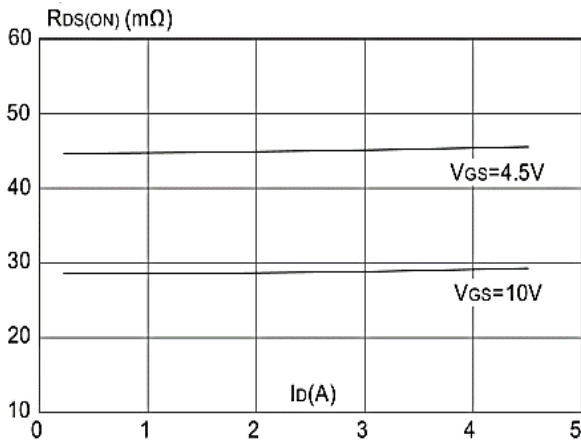
**N-Typical Characteristics**



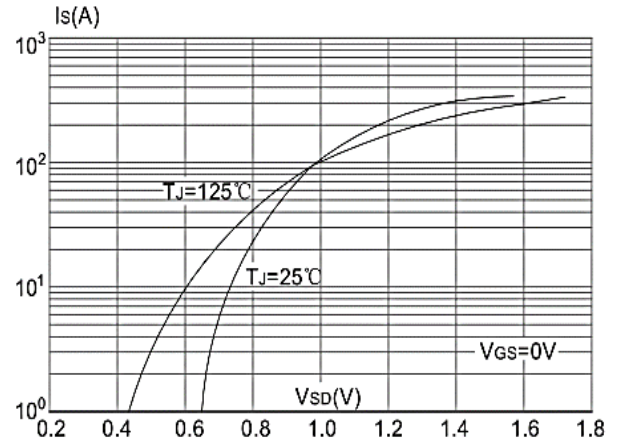
**Figure1: Output Characteristics**



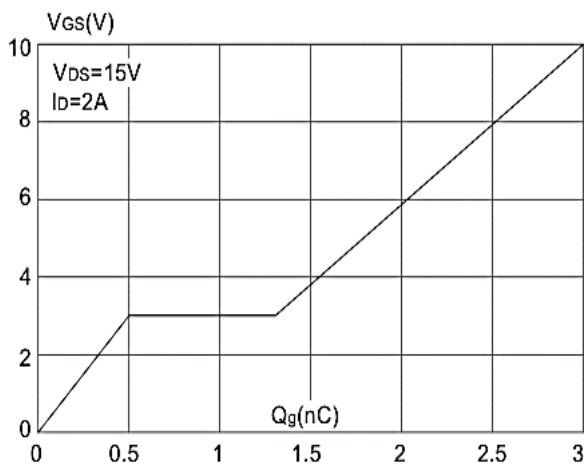
**Figure 2: Typical Transfer Characteristics**



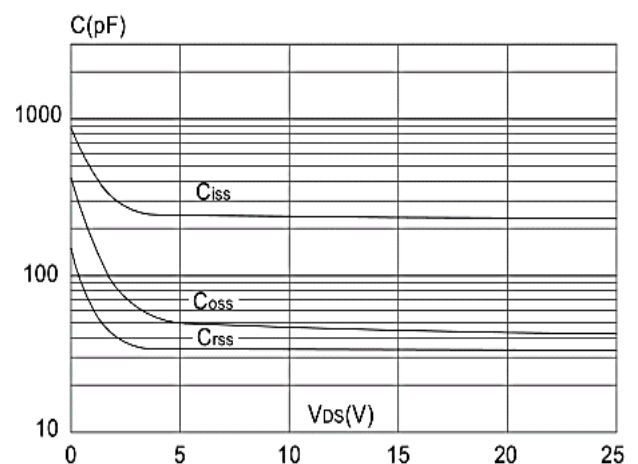
**Figure 3: On-resistance vs. Drain Current**



**Figure 4: Body Diode Characteristics**

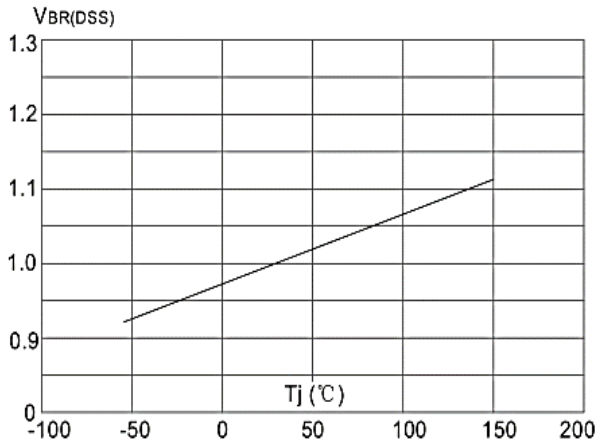


**Figure 5: Gate Charge Characteristics**

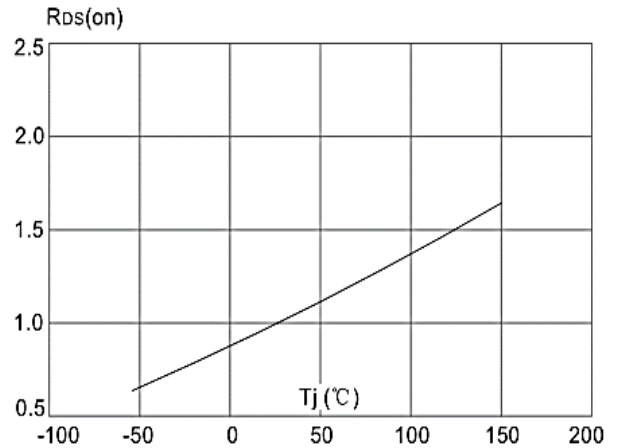


**Figure 6: Capacitance Characteristics**

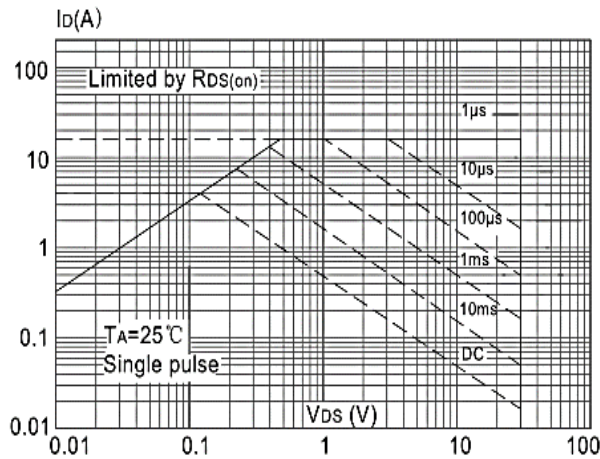
**N-Typical Characteristics**



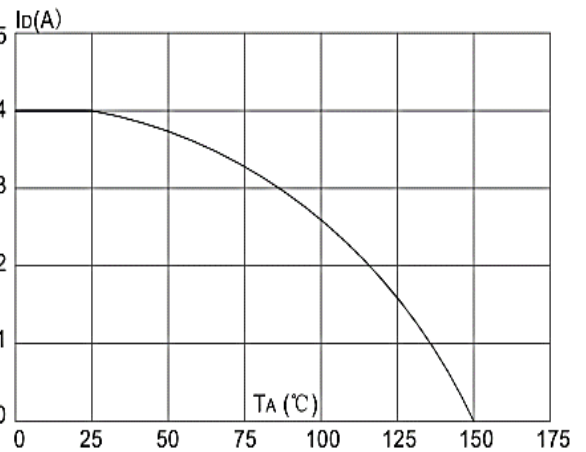
**Figure 7: Normalized Breakdown Voltage vs. Junction Temperature**



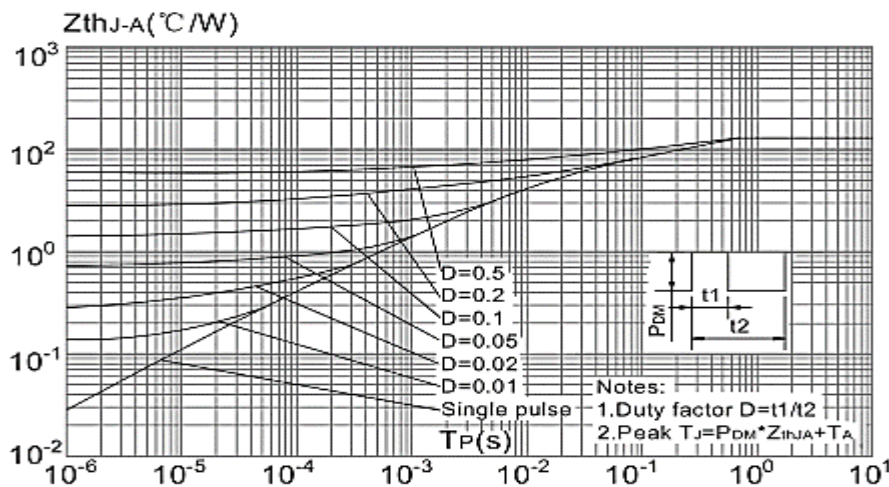
**Figure 8: Normalized on Resistance vs. Junction Temperature**



**Figure 9: Maximum Safe Operating Area vs. Case Temperature**



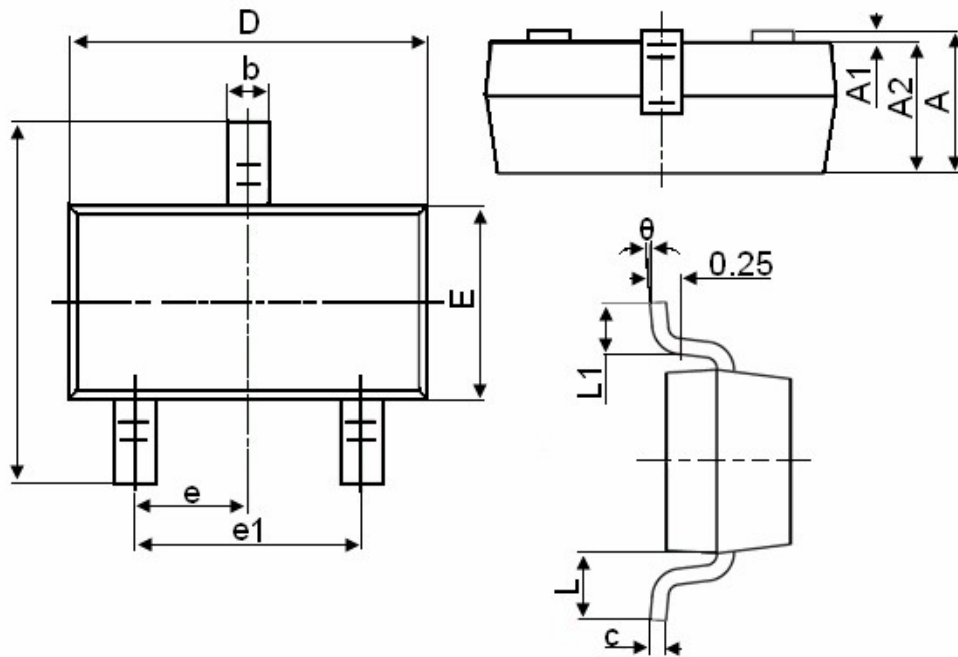
**Figure 10: Maximum Continuous Drain Current vs. Case Temperature**



**Figure.11: Maximum Effective Transient Thermal Impedance, Junction-to-Case**

Package Outline

SOT-23



Symbol	Dimensions in Millimeters	
	MIN.	MAX.
A	0.900	1.150
A1	0.000	0.100
A2	0.900	1.050
b	0.300	0.500
c	0.080	0.150
D	2.800	3.000
E	1.200	1.400
E1	2.250	2.550
e	0.950TYP	
e1	1.800	2.000
L	0.550REF	
L1	0.300	0.500
θ	0°	8°